

Future Directions in IC and Package Design Workshop, FDIP'04

sponsored by:



organized by:

CPMT Technical Committee on Electrical Design, Modeling, and Simulation (TC-EDMS)

October 24, 2004

Portland, Oregon

The goal of this workshop is to provide a forum to address the future needs associated with the design of next generation ICs and packages. The Technical Program Committee will solicit invited presentations from experts in the university and industrial communities. The workshop will be held in conjunction with the **IEEE Topical Meeting on Electrical Performance of Electronic Packaging** in order to enhance this conference with presentations that give directions for future requirements and developments in the area of electrical analysis and design. The workshop will foster active participation and discussions from all the speakers and attendees during the meeting.

The following talks are planned:

- *Gigascale Integration – Design Challenges and Opportunities, Shekhar Borkar, Intel Corporation*
- *Emerging Trends in High-Speed Interconnects and Packaging Engineering, Sergio Camerlo, Cisco Systems*
- *Analog RF CMOS and Optical Design Techniques for 10+ Gbps Datacom, Martin Schmatz, IBM Corporation*
- *Power Distribution: Status and Challenges, Madhavan Swaminathan, Georgia Institute of Technology*
- *Signal Integrity Modeling and Simulation for IC/Package Co-Design, Ching-Chao Huang, Optimal Corporation*
- *Current and Future Directions in Simulator Development, Sani Nassif and Jaijeet Roychowdhury from IBM Corporation and University of Minnesota*

Workshop Chairs:

Alina Deutsch
IBM Watson Research Center

Madhavan Swaminathan
Georgia Institute of Technology

Technical Program Committee:

Tawfik Arabi – Intel Oregon
Andreas Cangellaris - University of Illinois
Moises Cases - IBM Austin
Chi-Shih Chang – Consultant
Paul Franzone - North Carolina State University
Hartmut Grabinski - University of Hanover, Germany
Harold Hosack - Semiconductor Res. Corp.
Lewis Terman – IBM Watson Research

Mahadevan Iyer - IME, Singapore
George Katopis - IBM Poughkeepsie
Istvan Novak - SUN
Toshio Sudo - Toshiba, Japan
Gregory Taylor - Intel Oregon
John Prince – University of Arizona
Ryszard Vogel - Nokia, Finland

Workshop will be held at the Hilton Portland and Executive Tower, 921 SW Sixth Ave., Portland, OR 97204, 503-226-1611. The hotel is holding a block of rooms at \$99.00 (no tax). Reservations must be made by September 30, 2004 in order to guarantee this rate. Be sure to mention that you are attending the EPEP conference in order to secure this rate. For more information on the hotel go to <http://www.portland.hilton.com>

Additional information may be obtained from the workshop chairs:

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Attendees interested in the workshop will be charged a \$60.00 fee that will cover afternoon refreshments, digest of abstracts, and posting of the foils on the CPMT Society TC-EDMS web site. All attendees must register by September 13, 2004 using the EPEP'04 website at www.epep.org in order to assure that the workshop is being held. On-site registrants will be admitted depending on availability of seating.